

October 2008

FJA4210 PNP Epitaxial Silicon Transistor

- Audio Power Amplifier
- High Current Capability : I_C= -10A
- High Power Dissipation
- Wide S.O.A
- Complement to FJA4310



Absolute Maximum Ratings* T_a = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{CBO}	Collector-Base Voltage	-200	V
V _{CEO}	Collector-Emitter Voltage	-140	V
V _{EBO}	Emitter-Base Voltage	-6	V
l _C	Collector Current (DC)	-10	Α
I _B	Base Current (DC)	-1.5	Α
P _C	Collector Dissipation (T _C =25°C)	100	W
T _J	Junction Temperature	150	°C
T _{STG}	Storage Temperature	- 55 ~ 150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Electrical Characteristics* Ta=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
BV _{CBO}	Collector-Base Breakdown Voltage	I _C =-5mA, I _E =0	-200			V
BV _{CEO}	Collector-Emitter Breakdown Voltage	I _C =-50mA, R _{BE} =∞	-140			V
BV _{EBO}	Emitter-Base Breakdown Voltage	I _E =-5mA, I _C =0	-6			V
I _{CBO}	Collector Cut-off Current	V _{CB} =-200V, I _E =0			-10	μА
I _{EBO}	Emitter Cut-off Current	V _{EB} =-6V, I _C =0			-10	μА
h _{FE}	* DC Current Gain	V_{CE} =-4V, I_{C} =-3A	50		180	
V _{CE} (sat)	Collector-Emitter Saturation Voltage	I _C =-5A, I _B =-0.5A			-0.5	V
C _{ob}	Output Capacitance	V _{CB} =-10V, f=1MHz		400		pF
f _T	Current Gain Bandwidth Product	V _{CE} =-5V, I _C =-1A		30		MHz

^{*} Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

h_{FE} Classification

Classification	R	0	Y
h _{FE}	50 ~ 100	70 ~ 140	90 ~ 180

Typical Characteristics

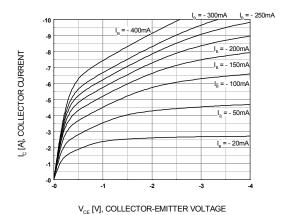


Figure 1. Static Characterstic

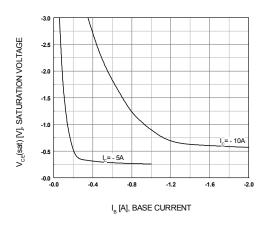


Figure 3. $V_{CE}(sat)$ vs. I_{B} Characteristics

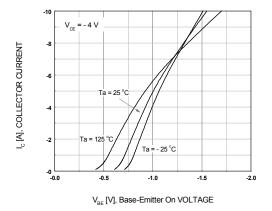


Figure 5. Base-Emitter On Voltage

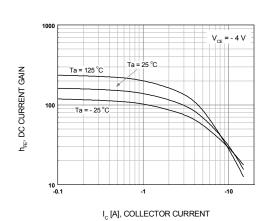


Figure 2. DC current Gain

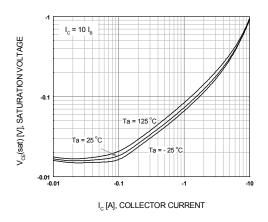


Figure 4. Collector-Emitter Saturation Voltage

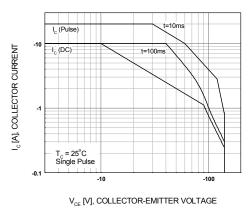


Figure 6. Forward Bias Safe Operating Area

Typical Characteristics (Continued)

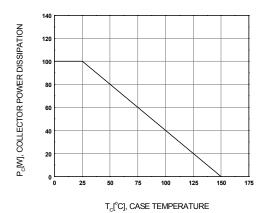
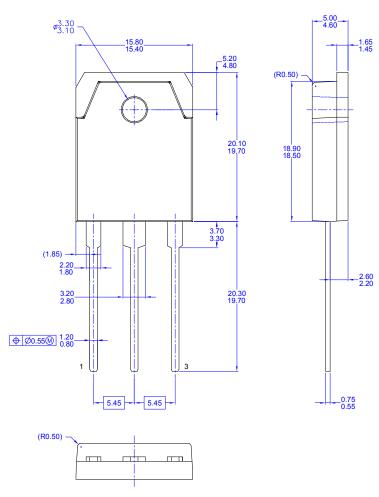


Figure 7. Power Derating

Package Dimension (TO-3P)



NOTES:

- NOTES:

 A) THIS PACKAGE CONFORMS TO EIAJ
 SC-65 PACKAGING STANDARD.

 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONING AND TOLERANCING PER
 ASME14.5 1973.

 D) DIMENSIONS ARE EXCLUSIVE OF BURRS,
 MOLD FLASH, AND TIE BAR EXTRUSIONS.
 E) DRAWING FILE NAME: TO3P03AREV2.





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